

# Summary of the SRF Materials Workshop

held 29-31 October at Michigan State Univ.  
hosted by MSU, NSCL, and Fermilab  
<http://meetings.nscl.msu.edu/srfmatsci/>



Presented by Lance Cooley  
SRF Materials Group Leader, Fermilab  
On behalf of the Program Committee

# Overview

- Fourth in a series of largely domestic workshops in the spirit of the Gordon Conferences
- General themes: end-use pull, industry achievements, materials science, processing innovations, fundamentals and tutorials
- Attendees are 40% Academic, 40% Lab, 20% Industry / Small Business
- Charge: *Build connections between fundamental materials science and SRF technology to understand limits, validate processes, and seek breakthroughs in performance.*

# Program

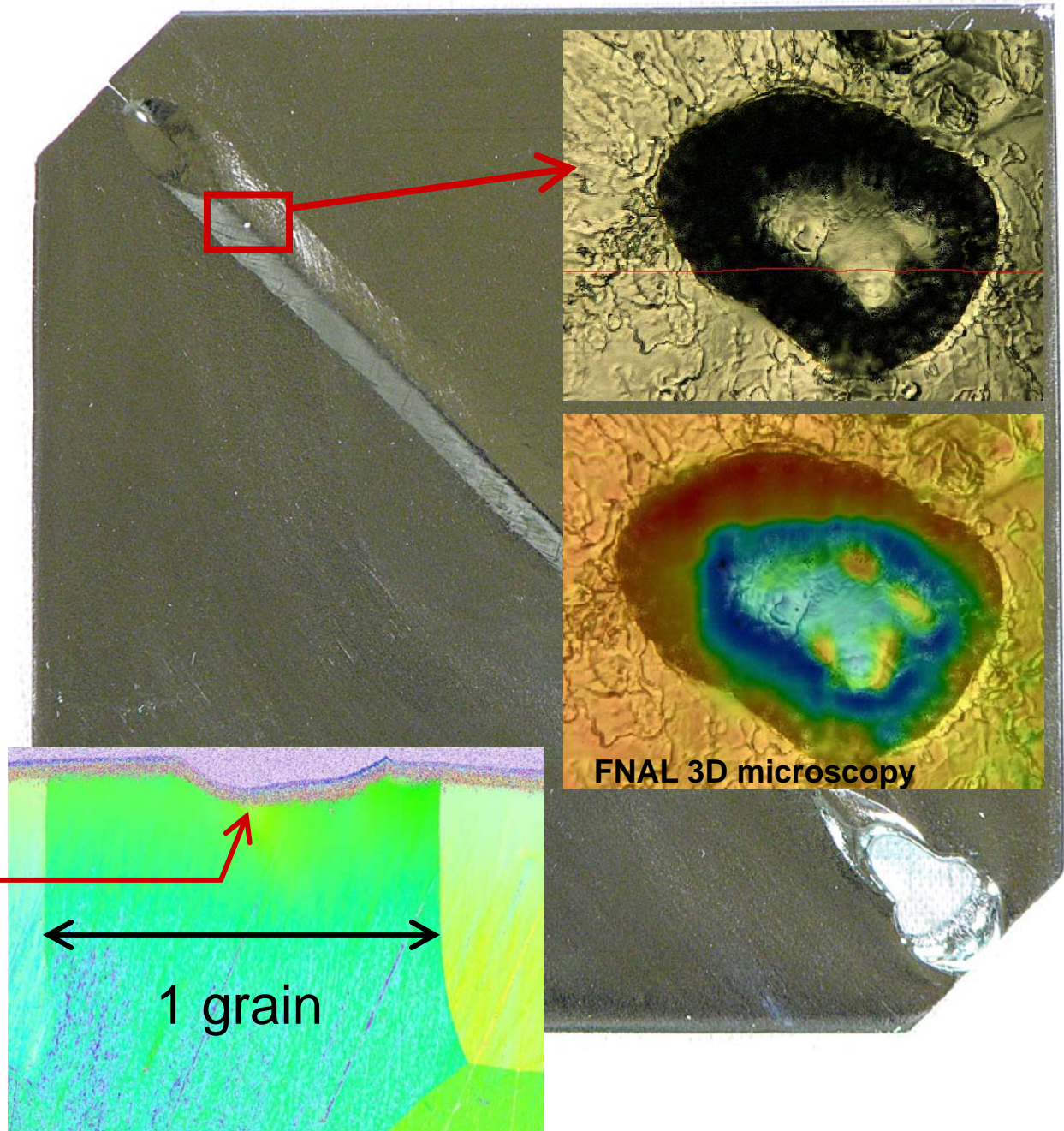
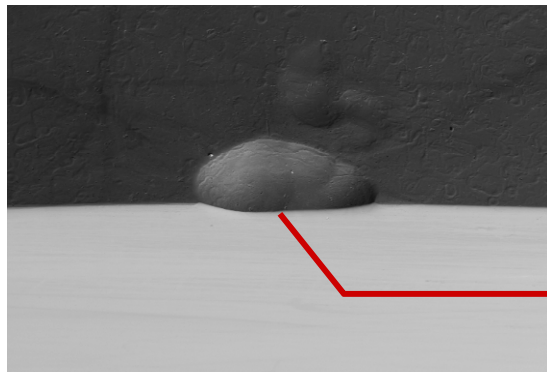
1. Materials R&D Drivers – updates from ILC, TTC, and other recent cavity tests
2. Removing or Avoiding Extrinsic Performance Limits
  - Focus on possible origins of weld / etch pits: do they originate from sheet forming? Welding? Electropolishing?
3. Understanding and Achieving Intrinsic Limits
  - Overviews of atomic layer deposition and flux-line heating
4. Beyond Niobium
5. Processing Science and Innovations
6. Seamless Forming
  - Tutorial on seamless forming

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Weld pits have  
been made in  
the laboratory

*Below: Cross-section of  
defect cut, polished,  
and imaged by  
orientation microscopy  
at Florida State*



**Fermilab**

Cooley – Main Linac - 2008 ILCTA 5



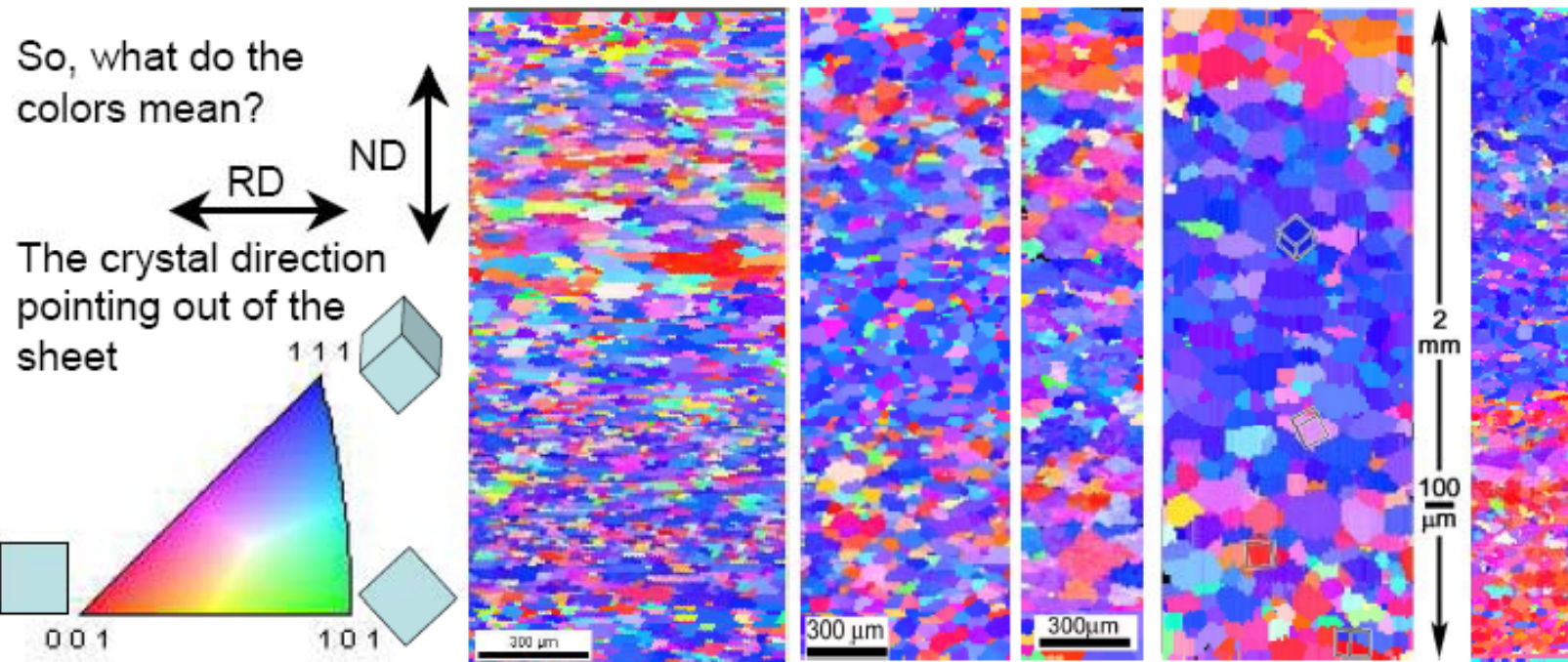
# Welding

- Bob Salo – Sciaky
- A moving electron gun may be preferred to a moving work piece
- A 50  $\mu\text{m}$  “defect” is not recognized as a defect in post-weld QA. “Weld porosity” is typically quoted in the 0.2 mm range and higher.



# Rolling to make sheet metal ... controlling microstructure and texture (grain orientations)

- Consistency is a challenge... Producers start with a hunk of ingot, and then use combination of breakdown forging, annealing, rolling to hopefully get a uniform microstructure
  - does initial ingot orientation haunt the microstructure at the end ?
- We have never seen the same texture/microstructure twice... !



# Observations and Speculations

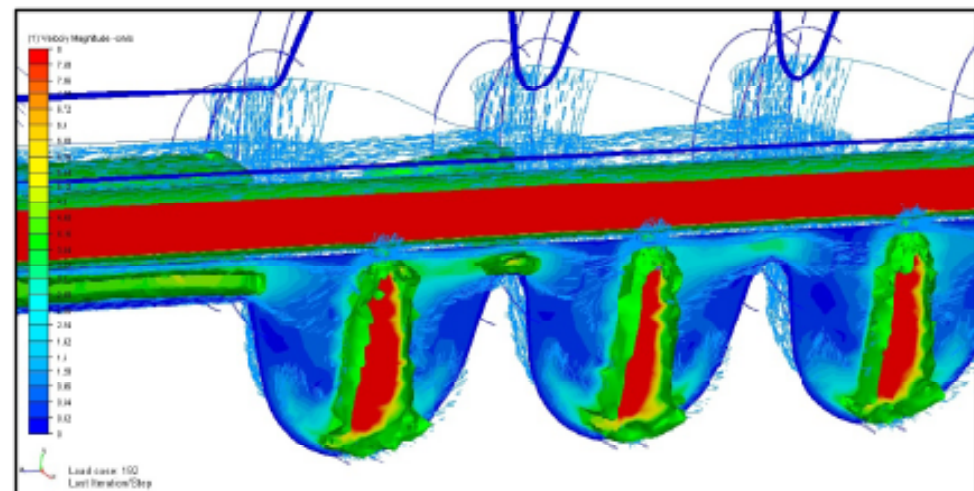
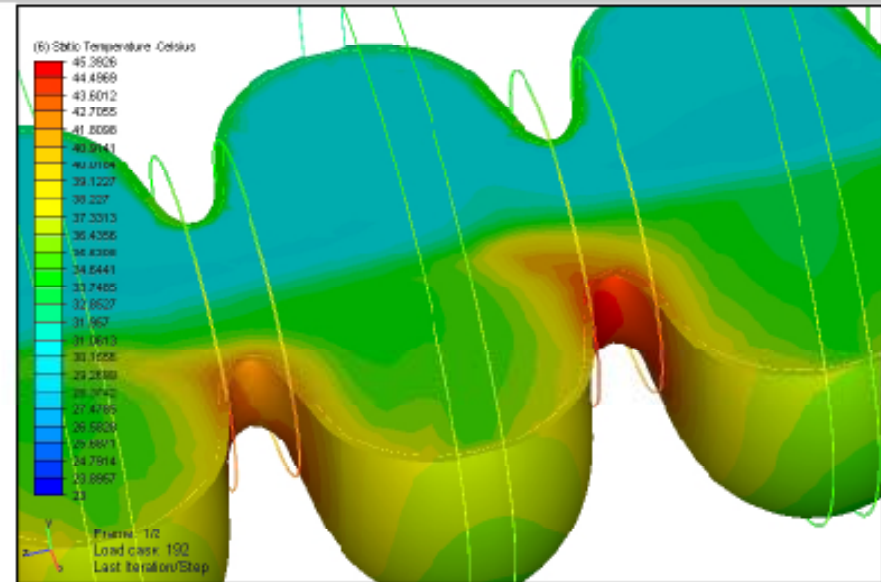
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- From making an ingot to final function, dislocations are an omnipresent enabler and suspect,
  - Additional suspects: H, O, impurities, interfaces, magnetic fields, surface energy
  - Dislocations can be removed most effectively by recrystallization;
  - Recovery leaves substructure that is oriented in crystallographic directions
- Does Nb love its dislocations so much that it will not let us take them away?
- Is the perfect cavity a recrystallized single crystal with dislocation segments **not** lined up in a radial direction?



# Electropolishing?

- There are dramatic variations in temperature and flow conditions on the surface of an “electropolishing” cavity.
- The local parameter sets are well outside those identified as “desired” by small sample tests.
- Historical measurements identified **20-35 C** as producing the lowest surface roughness (under static flow conditions).



# Electropolishing?

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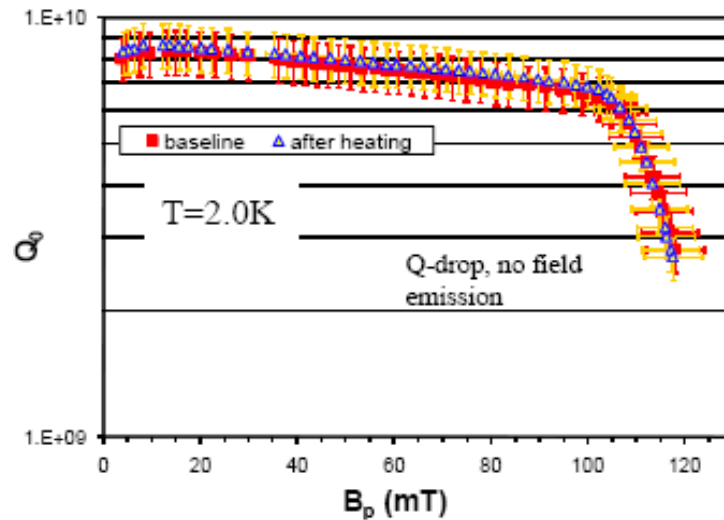
- At present, there is no bridge from controlled sample tests to the actually-used “electropolishing” parameter set.
  - Temperatures present are well outside of the “recommended” range.
  - Flow rates are variable and in a range not yet characterized via controlled sample analysis.
- Protocols applied to niobium cavities have been found empirically to (often, but not reliably) produce “good” results.
- **There exists minimal technical basis for contending that the transformation of the surface by “electropolishing” is understood and thus predictable or optimized.**
- Is there a significant *etching* component yet in present protocols?

# Program

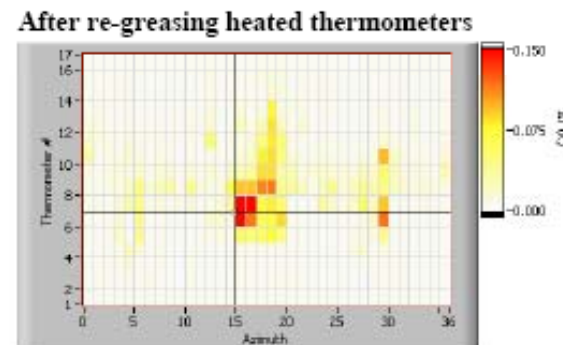
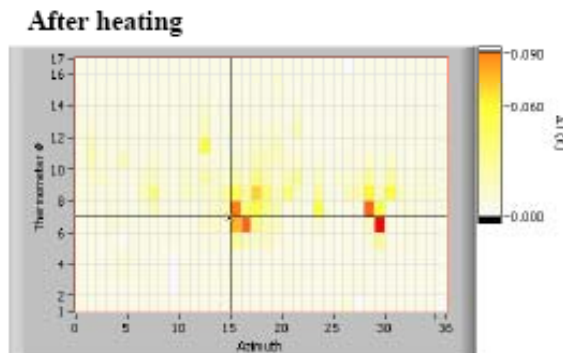
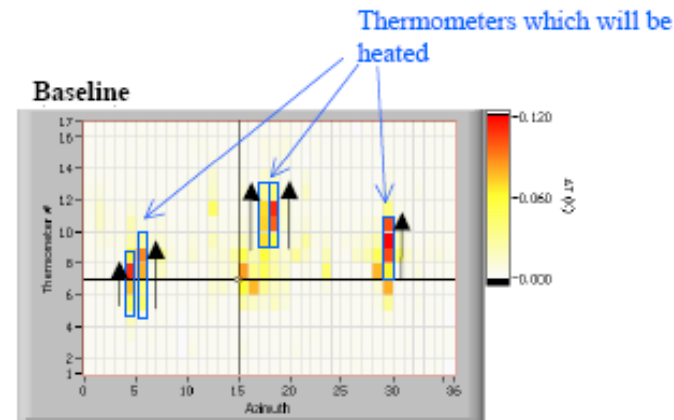
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# Flux “annealing” redistributes hot spots

More effective in large-grain cavities due to lower pinning



$$R_{res} = 12.9 \pm 1.2 \text{ n}\Omega \text{ baseline}$$
$$R_{res} = 12.2 \pm 1.3 \text{ n}\Omega \text{ after heating}$$

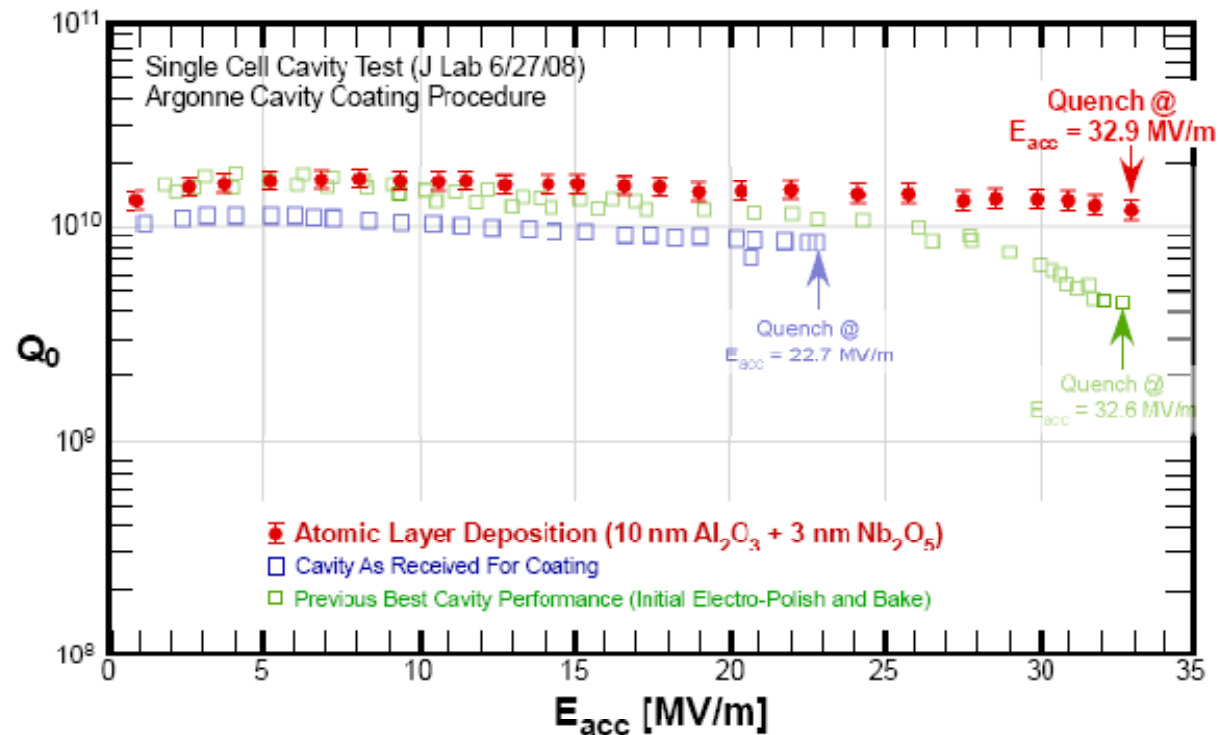


Re-distribution  
of “hot-spots”



# Atomic Layer Deposition appears to work

J Lab Cavity: After ALD Synthesis (10 nm  $\text{Al}_2\text{O}_3$  + 3 nm  $\text{Nb}_2\text{O}_5$ )



- Only last point shows detectable field emission.
- 2<sup>nd</sup> test after 2<sup>nd</sup> high pressure rinse. (1<sup>st</sup> test showed field emission consistent with particulate contamination)



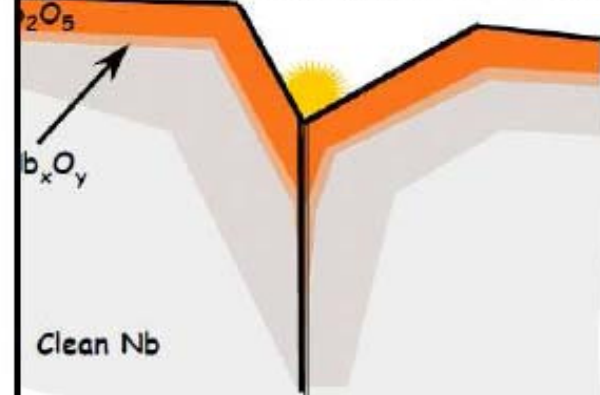
ILLINOIS INSTITUTE OF TECHNOLOGY Jefferson Lab

SRF Materials Workshop;  
MSU, October 29-31, 2008

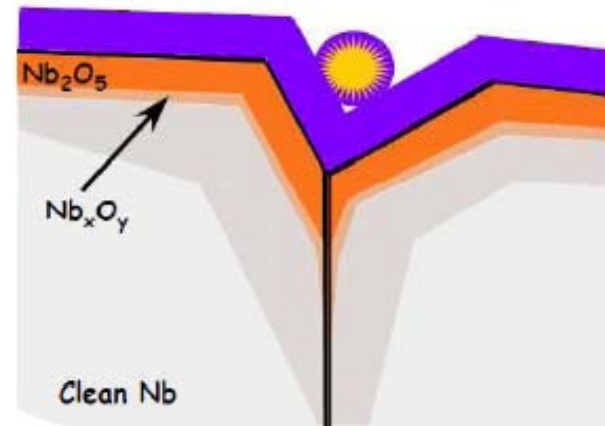
# Permanent cavity coatings?

## Fixing Niobium surfaces

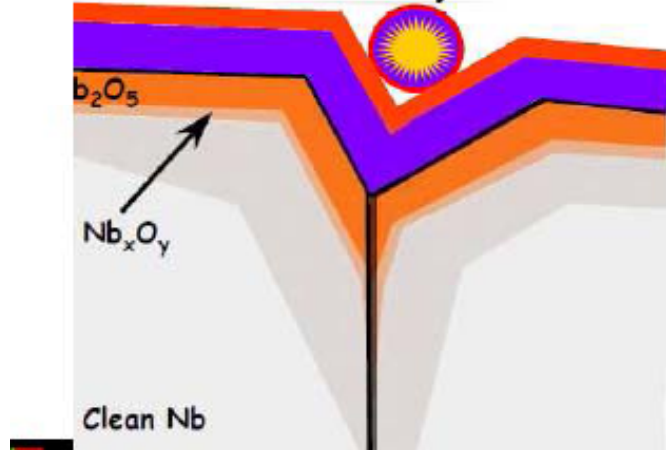
1. Begin with EP, Clean, Tested Cavity



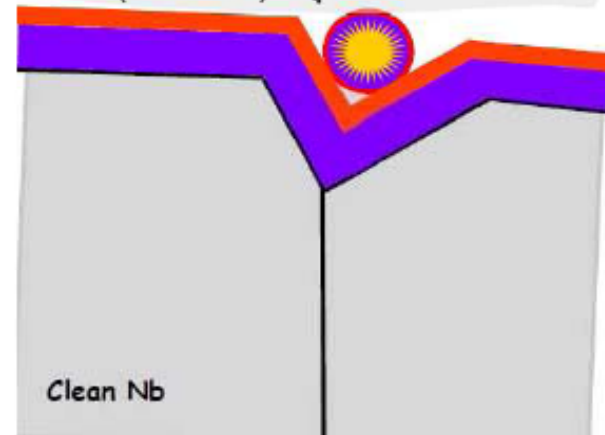
2. ALD with 10 nm of  $\text{Al}_2\text{O}_3$



3. Add a low secondary electron emitter



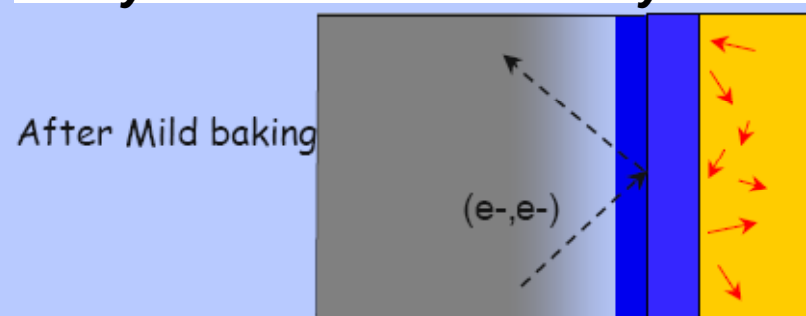
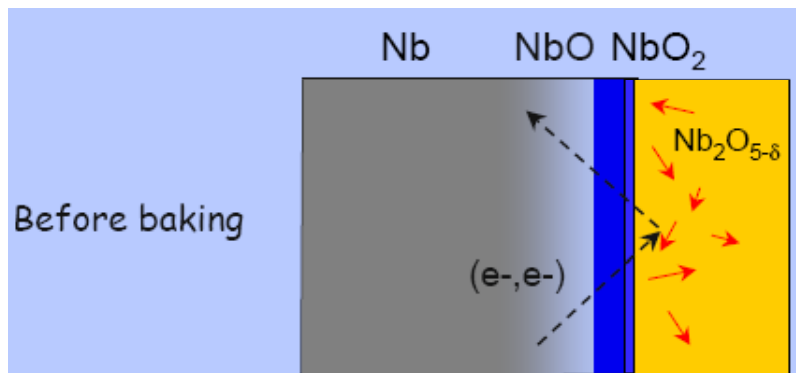
4. Bake ( $>400^\circ\text{C}$ ) to "dissolve O into bulk"



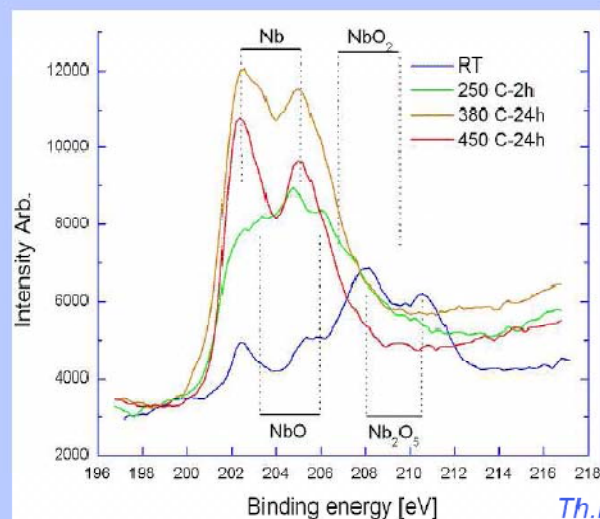
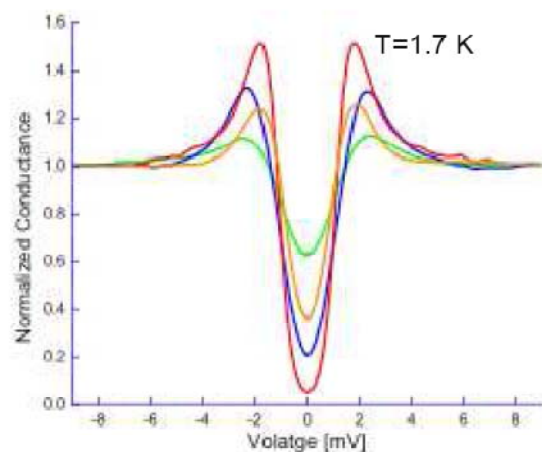
# Explanation of the baking effect?

J. Zasadzinski, T Proslir, M Pellin

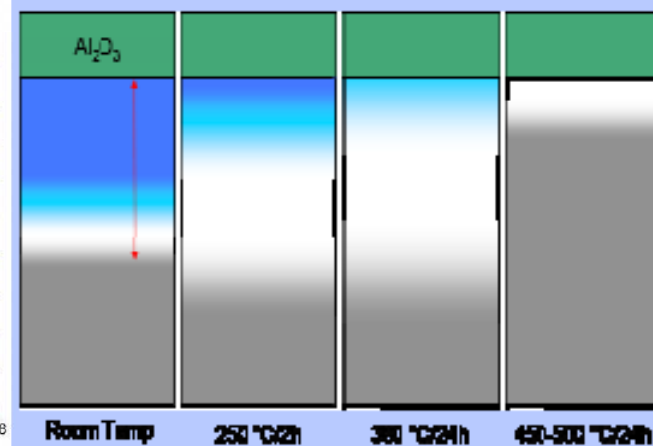
***Oxygen defects in  $Nb_2O_5$  are magnetic, break Cooper pairs when close. But they can be annealed away.***



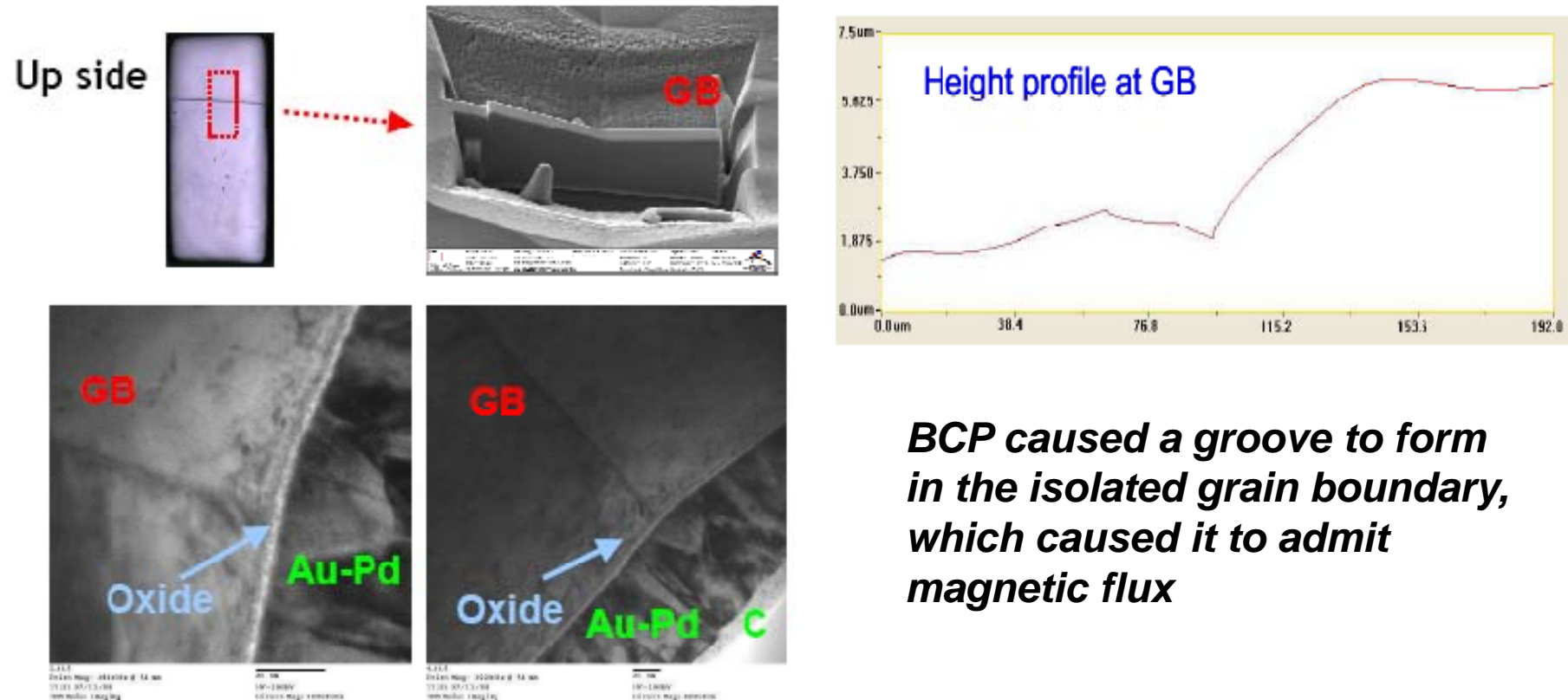
$Al_2O_3$  Protective layer, diffusion barrier



Schematic oxide evolution



# Evaluation of flux penetration into a grain boundary



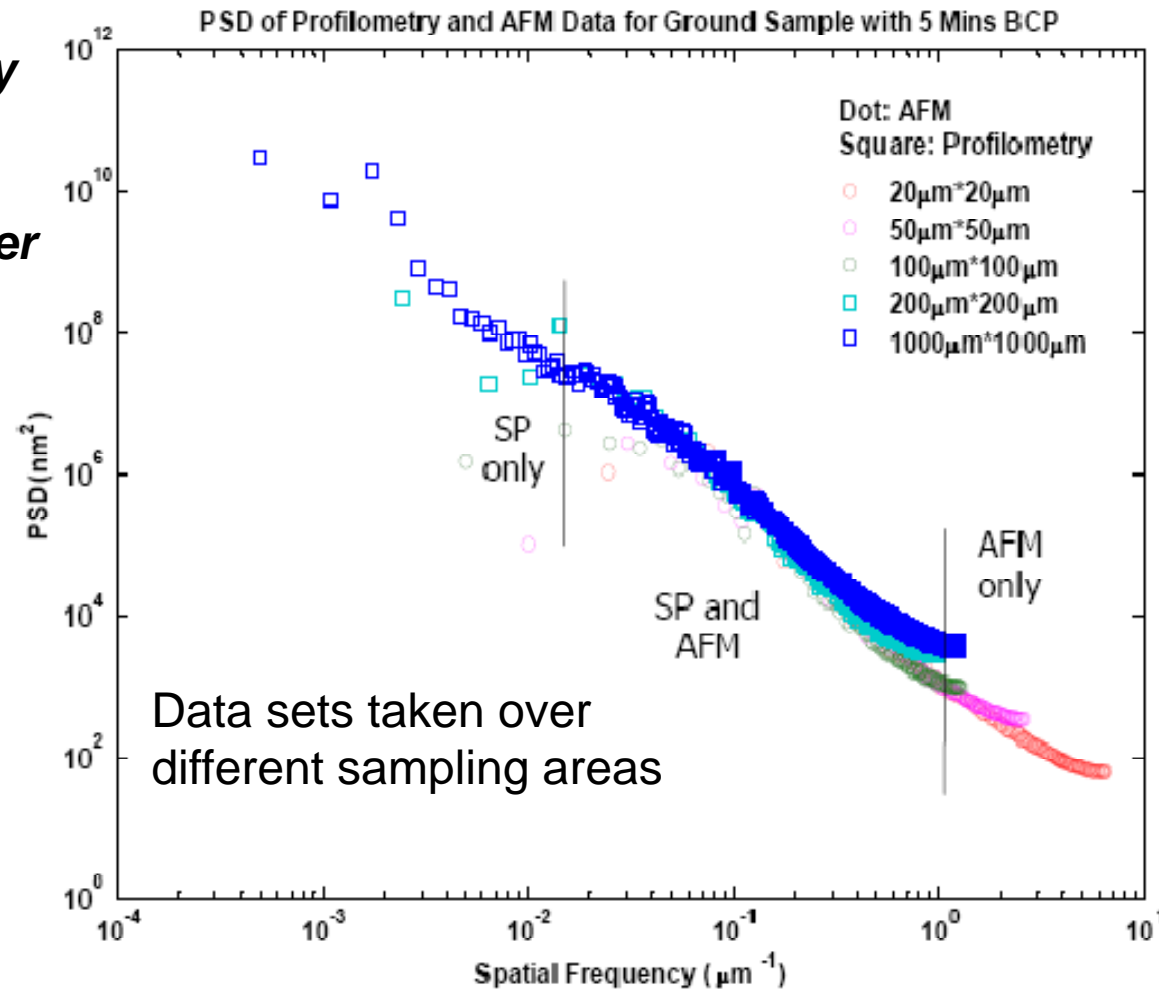
Z.H. Sung



# A better way to assess roughness

***Power spectral density  
incorporates  
roughness data from  
nanometer to millimeter  
scales***

***Why is scaling  
observed over 4  
decades?***

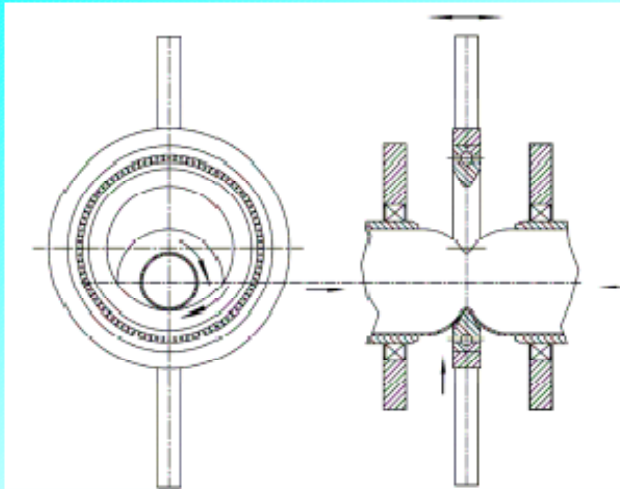


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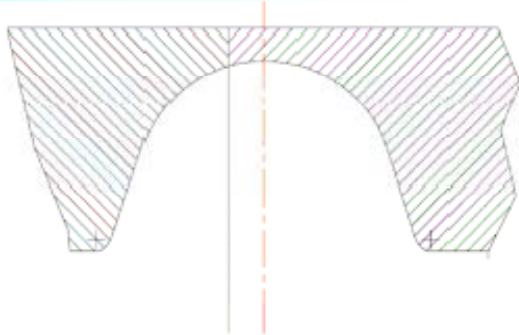
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# Seamless cavity forming - avoid welds

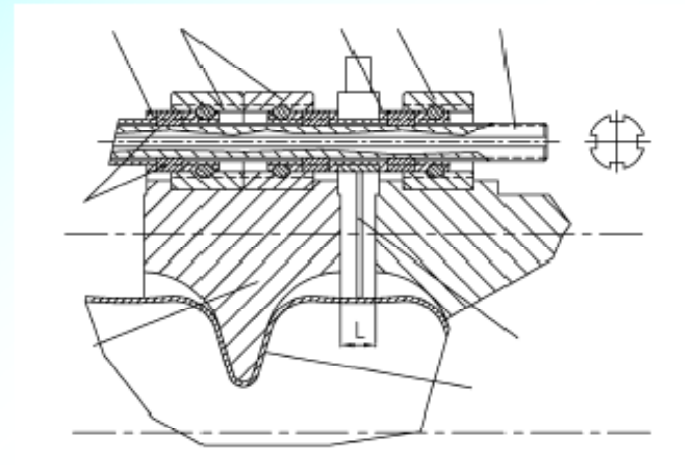
Some key ideas contributed to hydroforming success



Principle of diameter reduction in the tube end and in the tube middle



Nonsymmetrical mould for hydroforming

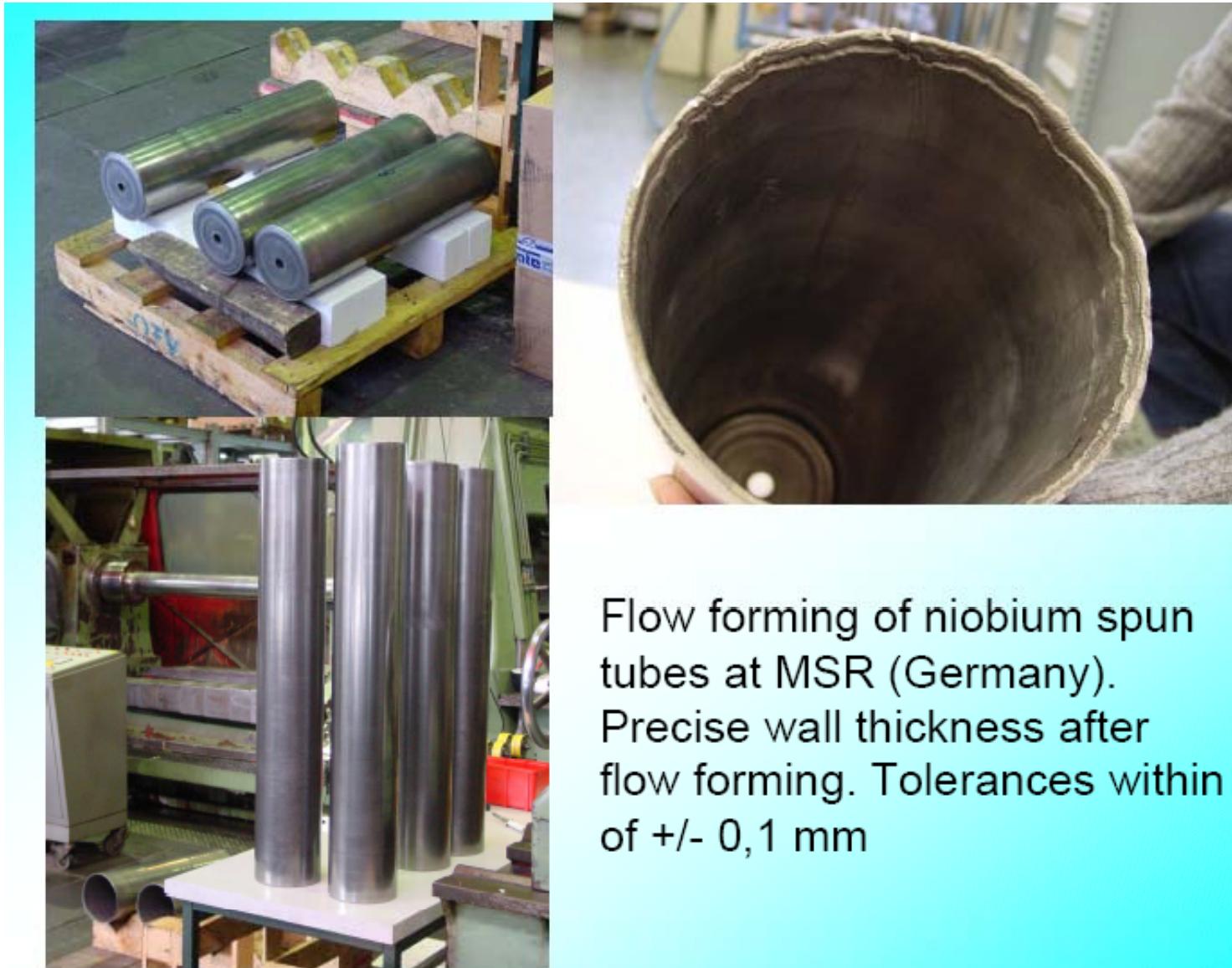


Synchronization mechanism for the final step of hydroforming

**Developed ideas summarized in the patent.**

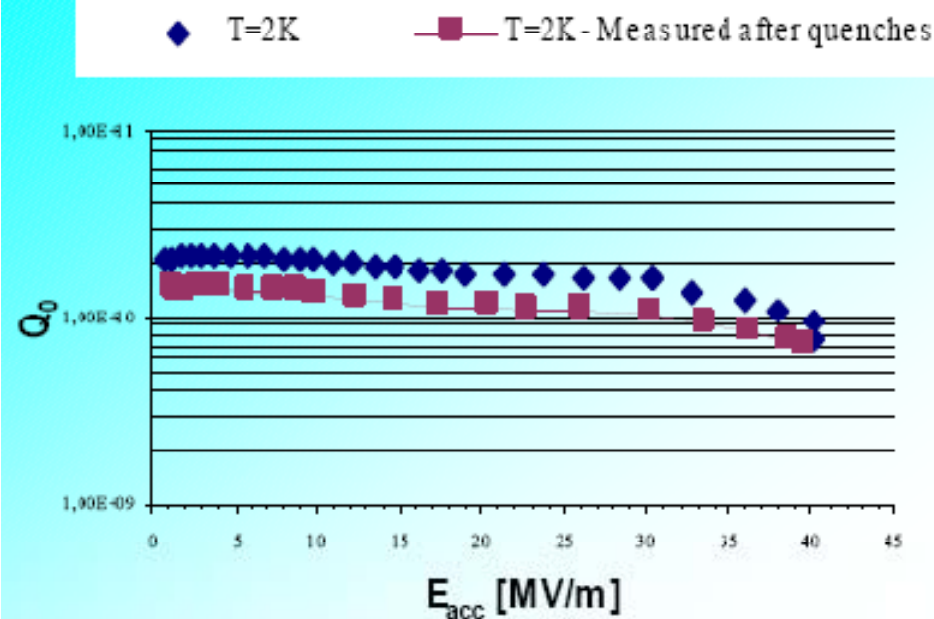
**W.Singer, I.Jelezov; No. 10 2007 037 835 ; 18 September 2008**

# Niobium tubes



Flow forming of niobium spun tubes at MSR (Germany). Precise wall thickness after flow forming. Tolerances within of  $\pm 0,1$  mm





NbCu single cell cavity 1NC2 produced at DESY by hydroforming from explosively bonded tube. Preparation and HF tests at Jeff. Lab: 180  $\mu\text{m}$  BCP, annealing at 800°C, baking at 140°C for 30 hours, HPR (P. Kneisel).

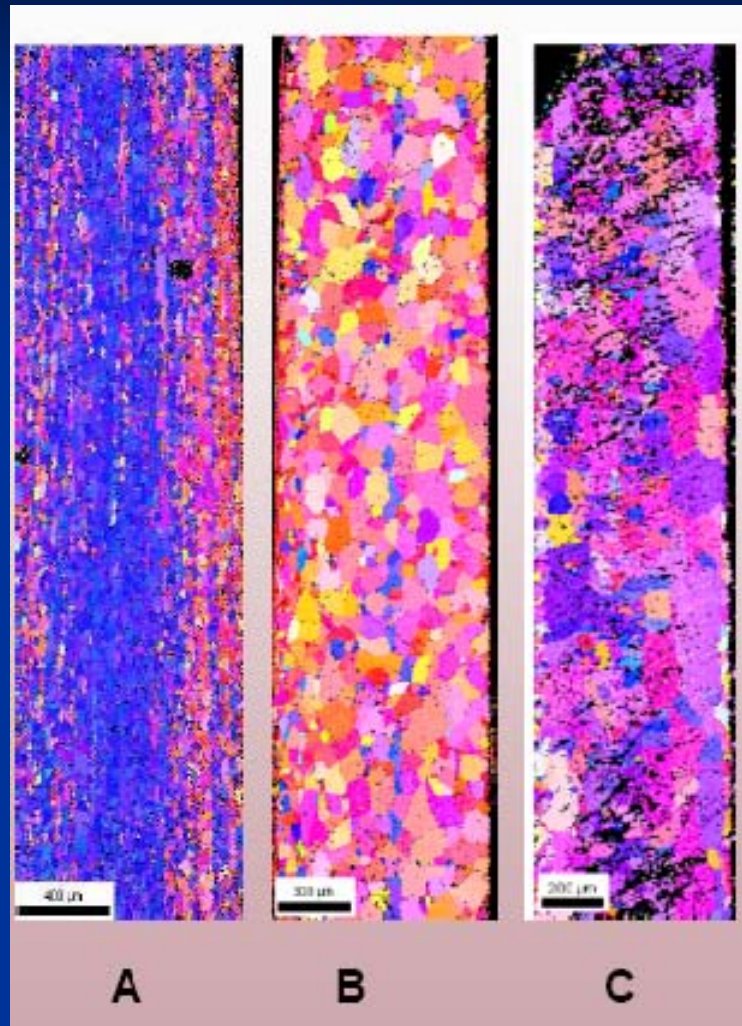


NbCu cavities hydroformed from explosively bonded tubes at DESY.

**40 MV/m without EP**

W. Singer. Hydroforming at DESY. SRF Materials Workshop, October 29-31, 2008, MSU, East Lansing, USA

# Ultra Fine Grain Processing/ECAE

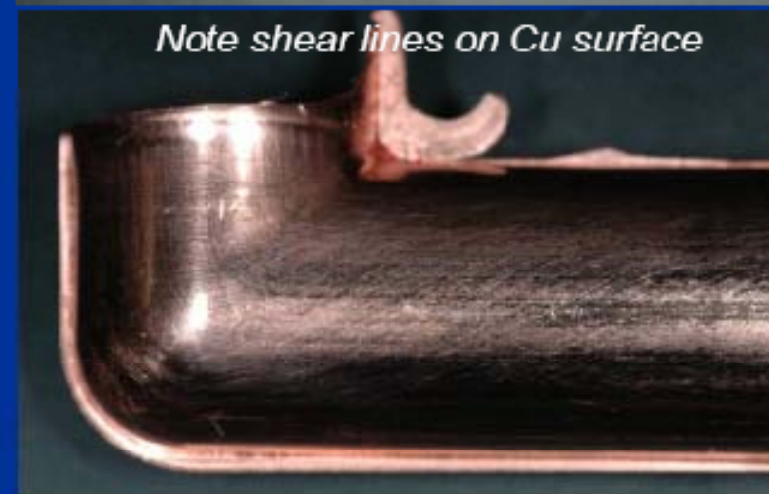


Hartwig – TAMU, Crooks – Black Labs

Bare 12.7 mm Niobium without Cu cladding



Stopped at 128,000 psi



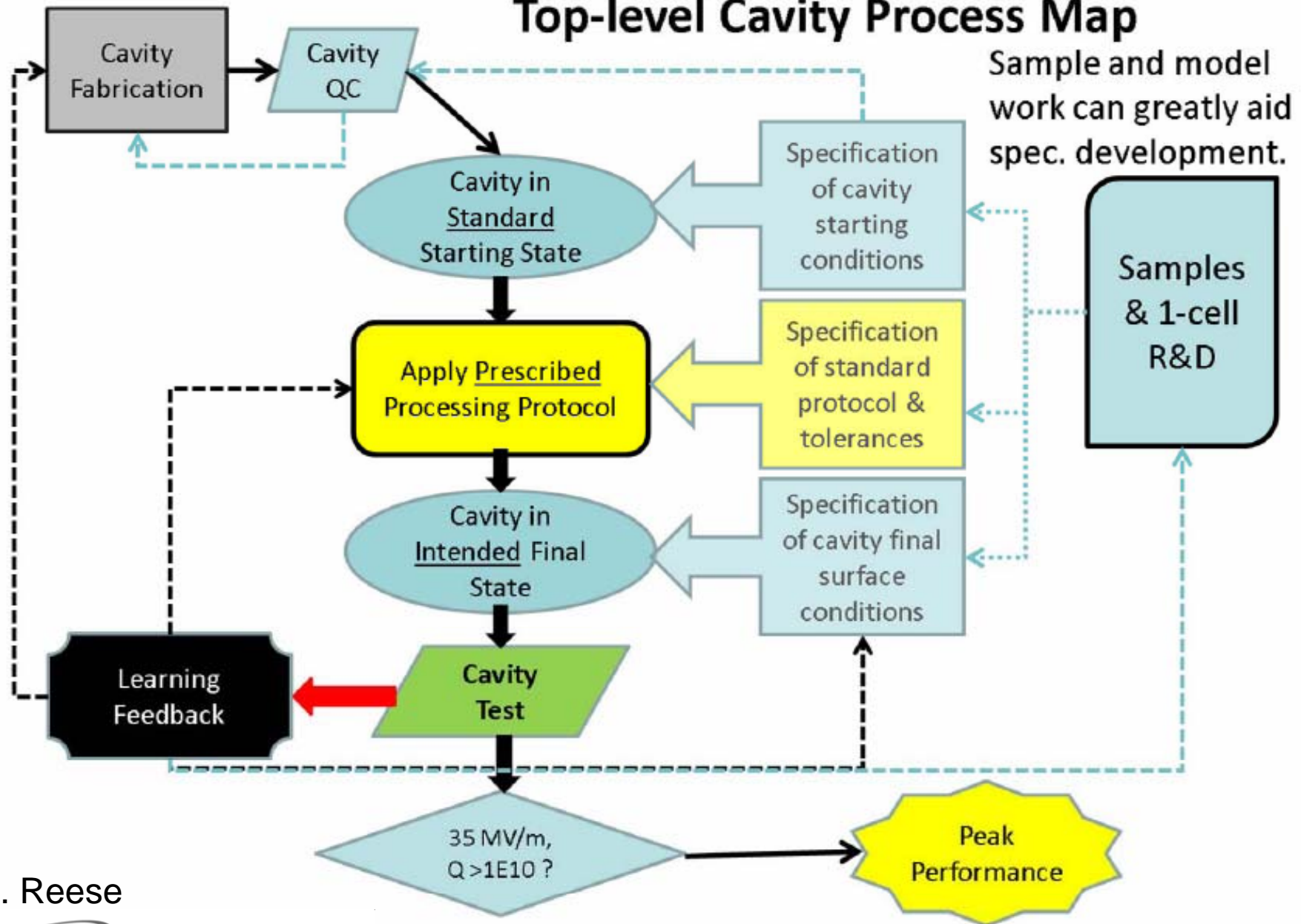
*Note shear lines on Cu surface*

Complete at 104,000 psi

# Summary



# Top-level Cavity Process Map



Sample and model work can greatly aid spec. development.

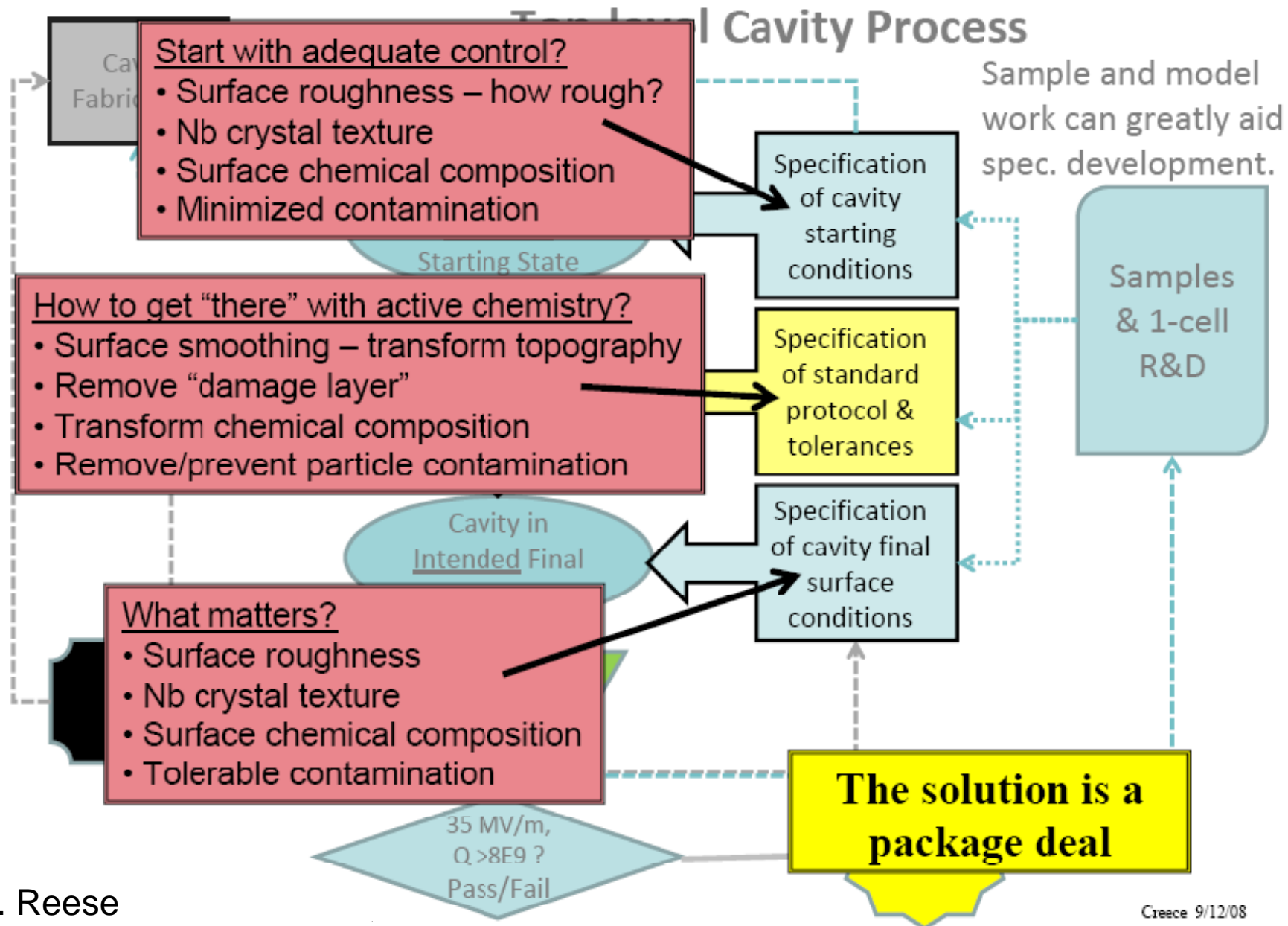
C. Reese

**Jefferson Lab**

Thomas Jefferson National Accelerator Facility

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C. Reese